

CGHV1F006S

6 W, DC - 15 GHz, 40 V, GaN HEMT

Description

The CGHV1F006S is an unmatched, gallium nitride (GaN) high electron mobility transistor (HEMT) designed specifically for high efficiency, high gain and wide bandwidth capabilities. The device can be deployed for L, S, C, X and Ku-Band amplifier applications. The datasheet specifications are based on a C-Band (5.5 - 6.5 GHz) amplifier. Additional application circuits are available for C-Band at 5.8 GHz - 7.2 GHz and X-Band at 7.9 - 8.4 GHz and 8.5 - 9.6 GHz. The CGHV1F006S operates on a 40 volt rail circuit while housed in a 3mm x 4mm, surface mount, dualflat-no-lead (DFN) package. Under reduced power, the transistor can operate below 40V to as low as 20V V_{DD}, maintaining high gain and efficiency.



Package Type: 3x4 DFN PN: CGHV1F006S

Features for 40 V in CGHV1F006S-AMP

- Up to 15 GHz Operation
- 8 W Typical Output Power
- 17 dB Gain at 6.0 GHz
- 15 dB Gain at 9.0 GHz

- Application circuits for 5.8 7.2 GHz, 7.9 8.4GHz, and 8.5 - 9.6 GHz.
- High degree of APD and DPD correction can be applied

Typical Performance Over 5.5 - 6.5 GHz ($T_c = 25$ °C), 40 V

Parameter	5.5 GHz	6.0 GHz	6.5 GHz	Units
Small Signal Gain	15.4	16.5	17.8	dB
Output Power @ P _{IN} = 28 dBm	38.6	39.3	39.0	dBm
Drain Efficiency @ P _{IN} = 28 dBm	55	57	52	%

Listing of Available Hardware Application Circuits / Demonstration Circuits

Application Circuit	Operating Frequency	Amplifier Class	Operating Voltage
CGHV1F006S-AMP1	5.85 - 7.2 GHz	Class A/B	40 V
CGHV1F006S-AMP2	7.9 - 8.4 GHz	Class A/B	40 V
CGHV1F006S-AMP3	8.5 - 9.6 GHz	Class A/B	40 V
CGHV1F006S-AMP4	4.9 - 5.9 GHz	Class A/B	20 V



Large Signal Models Available for ADS and MWO





Absolute Maximum Ratings (not simultaneous) at 25°C Case Temperature

Parameter	Symbol	Rating	Units	Notes
Drain-Source Voltage	V _{DSS}	120	V	25°C
Gate-to-Source Voltage	V _{GS}	-10, +2	V	25 C
Storage Temperature	T _{STG}	-65, +150	°C	
Operating Junction Temperature	T _J	225		
Maximum Forward Gate Current	I _{GMAX}	1.2	mA	25°C
Maximum Drain Current ¹	I _{DMAX}	0.95	A	25 C
Soldering Temperature ²	T _s	245	°c	
Case Operating Temperature ^{3,4}	T _c	-40, +150		
Thermal Resistance, Junction to Case ⁵	$R_{ heta JC}$	14.5	°C/W	85°C

Notes:

Electrical Characteristics (TC = 25°C), 40 V Typical

Characteristics	Symbol	Min.	Тур.	Max.	Units	Conditions	
DC Characteristics ¹							
Gate Threshold Voltage	V _{GS(th)}	-3.6	-3.0	-2.4	V _{DC}	$V_{DS} = 10 \text{ V}, I_{D} = 1.2 \text{ mA}$	
Gate Quiescent Voltage	V _{GS(Q)}	-	-2.7	-	V _{DC}	$V_{DS} = 40 \text{ V}, I_{D} = 60 \text{ mA}$	
Saturated Drain Current ²	I _{DS}	0.86	1.2	-	Α	$V_{DS} = 6.0 \text{ V}, V_{GS} = 2.0 \text{ V}$	
Drain-Source Breakdown Voltage	V _{(BR)DSS}	100	-	-	V _{DC}	$V_{GS} = -8 \text{ V}, I_{D} = 1.2 \text{ mA}$	
RF Characteristics ³ ($T_c = 25^{\circ}C$, $F_0 = 5$.925 GHz un	less othe	rwise no	ted)			
Small Signal Gain ^{3,4}	G	15.15	17.4	-	dB	$V_{DD} = 40 \text{ V}, I_{DQ} = 60 \text{ mA}, P_{IN} = 10 \text{ dBm}$	
Output Power ^{3,4}	Роит	37.5	38.7	-	dBm	V - 40 V I - 60 ··· A D - 25 5 dD···	
Drain Efficiency ^{3,4}	η	35	52	-	%	$V_{DD} = 40 \text{ V}, I_{DQ} = 60 \text{ mA}, P_{IN} = 25.5 \text{ dBm}$	
Output Mismatch Stress ⁴	VSWR	-	10:1	-	Ψ	No damage at all phase angles, $V_{DD} = 40 \text{ V}, I_{DQ} = 60 \text{ mA}, P_{IN} = 25.5 \text{ dBm}$	
Dynamic Characteristics							
Input Capacitance⁵	C _{GS}	_	1.3	_			
Output Capacitance ⁵	C _{DS}	-	0.31	_	pF	$V_{DS} = 40 \text{ V}, V_{gs} = -8 \text{ V}, f = 1 \text{ MHz}$	
Feedback Capacitance	C _{GD}	-	0.04	-			

Notes:

¹ Current limit for long term, reliable operation

² Refer to the Application Note on soldering

 $^{^{3}}$ Simulated at $P_{DISS} = 2.4 W$

 $^{^4}$ T $_c$ = Case temperature for the device. It refers to the temperature at the ground tab underneath the package. The PCB will add additional thermal resistance

 $^{^5}$ The R $_{\rm TH}$ for the application circuit, CGHV1F006S-AMP, with 31 (Ø11 mil) via holes designed on a 20 mil thick Rogers 5880 PCB, is 3.9°C/W. The total R $_{\rm TH}$ from the heat sink to the junction is 14.5°C/W + 3.9°C/W = 18.4°C/W

¹ Measured on wafer prior to packaging

² Scaled from PCM data

³ Measured in production test fixture. This fixture is designed for high volume testing at 5.925 GHz

 $^{^{\}text{4}}$ Unmodulated Pulsed Signal 100 $\mu s,$ 10% duty cycle

⁵ Includes package



Electrical Characteristics When Tested in CGHV1F006S-AMP1 at C-Band Under OQPSK

Characteristics	Symbol	Min.	Тур.	Max.	Units	Conditions			
RF Characteristics ¹ (T _c = 25	RF Characteristics¹ (T _c = 25 °C, F ₀ = 5.8 - 7.2 GHz unless otherwise noted)								
Gain	G	-	17.5	-	dB	$V_{DD} = 40 \text{ V}, I_{DQ} = 60 \text{ mA}, P_{IN} = 0 \text{ dBm}$			
Output Power ²	P _{out}	-	39	-	dBm	V = 40 V L = 60 mA D = 27 dDm			
Drain Efficiency ²	η	-	55	-	%	$V_{DD} = 40 \text{ V}, I_{DQ} = 60 \text{ mA}, P_{IN} = 27 \text{ dBm}$			
OQPSK ³	ACLR	-	-36	-	dBc	$V_{DD} = 40 \text{ V}, I_{DQ} = 60 \text{ mA}, P_{OUT} = 33 \text{ dBm}$			
Output Mismatch Stress ²	VSWR	-	10:1	-	Ψ	No damage at all phase angles, $V_{DS} = 40 \text{ V}, I_{DQ} = 60 \text{ mA}$			

Notes:

Typical Performance - CGHV1F006S-AMP1 at C-Band Under OQPSK

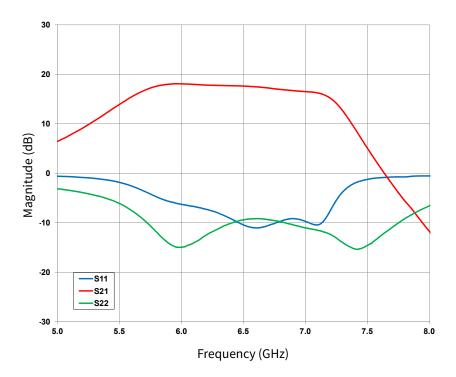


Figure 1. Typical Small Signal Response of CGHV1F006S-AMP1 Application Circuit $V_{DD} = 40 \text{ V}, I_{DO} = 60 \text{ mA}$

¹ Measured in CGH1F006S-AMP1 Application Circuit

² Pulsed 100 μs, 10% duty cycle

³ OQPSK modulated signal, 1.6 msps, PN23, Alpha Filter = 0.2 Offset = 1.6 MHz



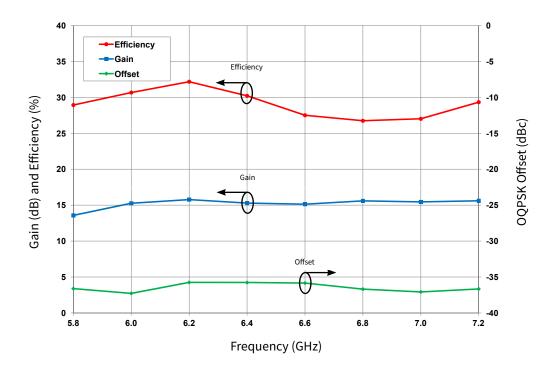


Figure 2. Typical Gain, Efficiency and OQPSK Performance vs Frequency $P_{OUT} = 33 \text{ dBm. V}_{DD} = 40 \text{ V}, I_{DQ} = 60 \text{ mA}$

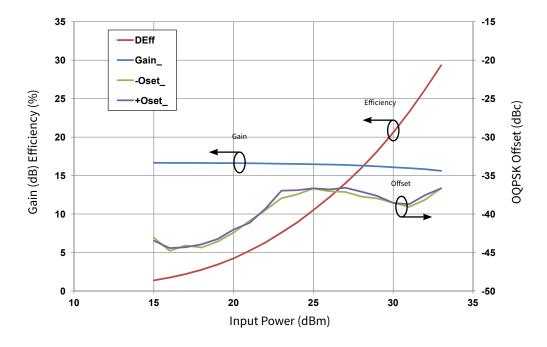


Figure 3. Typical Gain, Efficiency and OQPSK Performance vs Input Power OQPSK Transfer Frequency = 7.2 GHz, V_{DD} = 40 V, I_{DO} = 60 mA



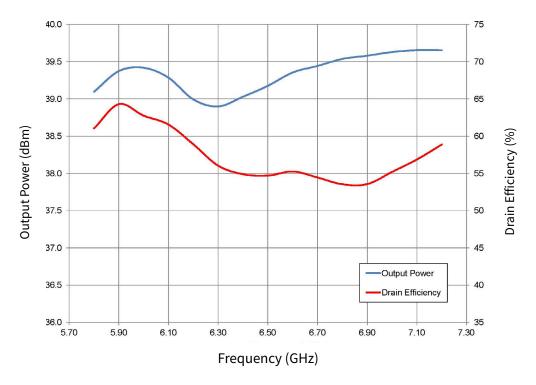
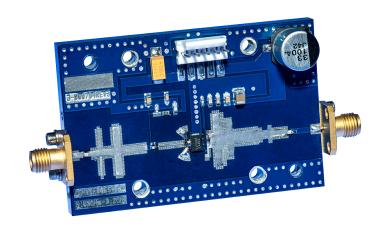


Figure 4. Typical Pulsed Power Response $V_{DD} = 40 \text{ V}, I_{DO} = 60 \text{ mA}, 100 \text{ } \mu\text{s}, 10\% \text{ Duty}, P_{IN} = 27 \text{ dBm}$

CGHV1F006S-AMP1 Application Circuit Bill of Materials, OQPSK

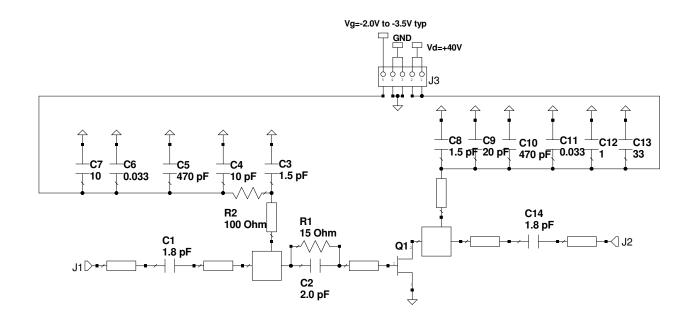
Designator	Description	Qty
R1	RES, 15 ohm, +1/-1%, 1/16 W, 0402	1
R2	RES, 100 ohm, +1/-1%, 1/16 W, 0603	1
C1, C14	CAP, 1.8 pF, ±0.1 pF, 0603, ATC	2
C2	CAP, 2.0 pF, ±0.1 pF, 0402, ATC	1
C3, C8	CAP, 1.5 pF, ±0.1 pF, 0402, ATC	2
C4	CAP, 10 pF, ±5%, 0603, ATC	1
C5, C10	CAP, 470 pF, 5%, 100 V, 0603, X	2
C6, C11	CAP, 33000 pF, 0805, 100V, X7R	2
C7	CAP, 10 μF, 16 V, TANTALUM	1
C9	CAP, 20 pF, ±5%, 0603, ATC	1
C12	CAP, 1.0 μF, 100V, 10% X7R, 1210	1
C13	CAP, 33 μF, 20%, G CASE	1
J1, J2	CONN, SMA, PANEL MOUNT JACK, FLANGE	2
	PCB, RT5880, 0.020" THK, CGHV1F006S	1
J3	HEADER RT>PLZ .1CEN LK 5POS	1
Q1	QFN TRANSISTOR CGHV1F006S	1

CGHV1F006S-AMP1 Application Circuit

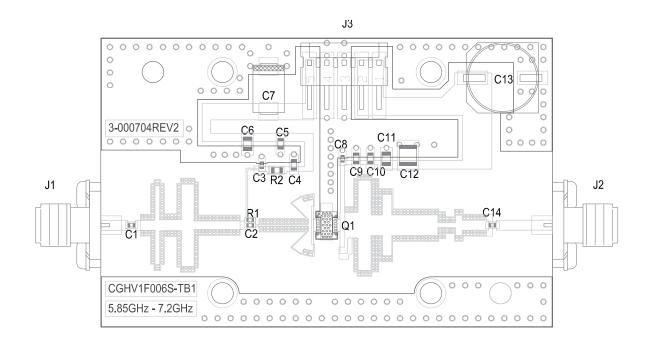




CGHV1F006S-AMP1 Application Circuit Schematic, OQPSK



CGHV1F006S-AMP1 Application Circuit Outline, OQPSK





Electrical Characteristics When Tested in CGHV1F006S-AMP2 at X-Band, SATCOM

Characteristics	Symbol	Min.	Тур.	Max.	Units	Conditions	
RF Characteristics ¹ ($T_c = 25^{\circ}$ C, $F_0 = 7.9 - 8.4$ GHz unless otherwise noted)							
Gain	G	-	15	-	dB	$V_{DD} = 40 \text{ V}, I_{DQ} = 60 \text{ mA}, P_{IN} = 0 \text{ dBm}$	
Output Power ²	P _{out}	-	39	-	dBm	$V_{DD} = 40 \text{ V}, I_{DO} = 60 \text{ mA}, P_{IN} = 28 \text{ dBm}$	
Drain Efficiency ²	η	-	55	-	%	V _{DD} = 40 V, I _{DQ} = 00 IIIA, I _{IN} = 20 UDIII	
OQPSK ³	ACLR	-	-37		dBc	$V_{DD} = 40 \text{ V}, I_{DQ} = 60 \text{ mA}, P_{OUT} = 33 \text{ dBm}$	
Output Mismatch Stress ²	VSWR	-	10:1	-	Ψ	No damage at all phase angles, $V_{DD} = 40 \text{ V}, I_{DQ} = 60 \text{ mA}, P_{IN} = 28 \text{ dBm}$	

Notes:

Typical Performance in Application Circuit CGHV1F006S-AMP2 at X-Band, SATCOM

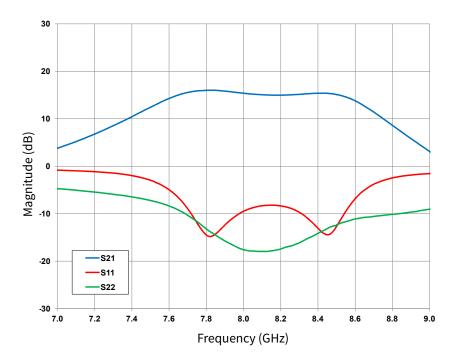


Figure 5. Typical Small Signal Response of CGHV1F006S-AMP2 Application Circuit V_{DD} = 40 V, I_{DQ} = 60 mA

¹Measured in CGHV1F006S-AMP2 Application Circuit

² Pulsed 100 μs, 10% duty cycle

³ OQPSK modulated signal, 1.6 msps, PN23, Alpha Filter = 0.2 Offset = 1.6 MHz



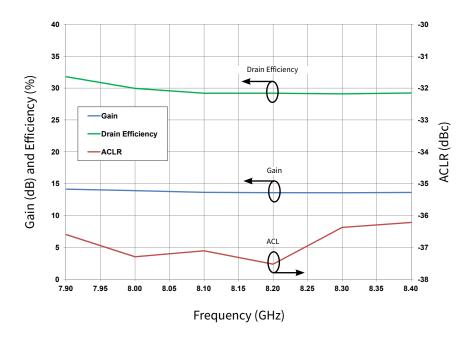


Figure 6. Typical OQPSK Response $V_{DD} = 40 \text{ V}, I_{DQ} = 60 \text{ mA}, 1.6 \text{ MSPS}, P_{OUT} = 33 \text{ dBm}$

Typical Performance in Application Circuit CGHV1F006S-AMP2

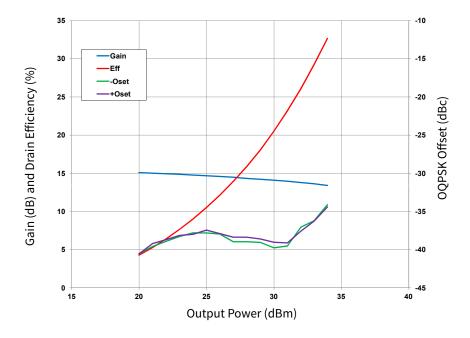


Figure 7. OQPSK Transfer Response $V_{DD} = 40 \text{ V}, I_{DO} = 60 \text{ mA}, 1.6 \text{ MSPS}, Frequency} = 8.4 \text{ GHz}$



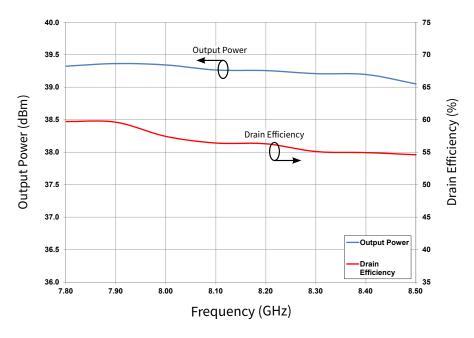
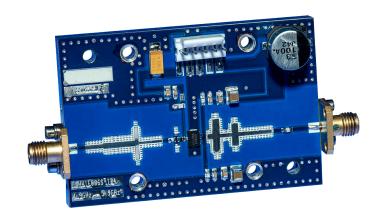


Figure 8. Typical Pulsed Power Response $V_{DD} = 40 \text{ V}$, $I_{DO} = 60 \text{ mA}$, $100 \text{ } \mu\text{s}$, 10% Duty, $P_{IN} = 28 \text{ dBm}$

CGHV1F006S-AMP2 Application Circuit Bill of Materials, SATCOM

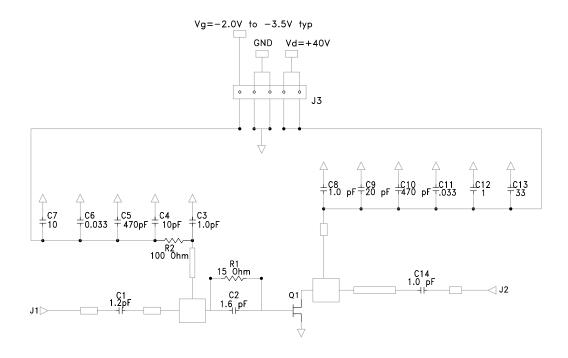
Designator	Description	Qty
R1	RES, 15 ohm, +1/-1%, 1/16 W, 0402	1
R2	RES, 100 ohm, +1/-1%, 1/16 W, 0603	1
C3, C8	CAP, 1.0 pF, ±0.05 pF, 0402, ATC	2
C14	CAP, 1.0 pF, ±5%, 0603, ATC	1
C1	CAP, 1.2 pF, ±5%, 0603, ATC	1
C2	CAP, 1.6 pF, ±5%, 0402, ATC	1
C4	CAP, 10 pF, ±5%, 0603, ATC	1
C5, C10	CAP, 470 pF, 5%, 100V, 0603, X	2
C6,C11	CAP, 33000 pF, 0805, 100V, X7R	2
C7	CAP, 10 μF, 16 V, TANTALUM	1
C9	CAP, 20 pF, ±5%, 0603, ATC	1
C12	CAP, 1.0 μF, 100V, 10%, X7R, 1210	1
C13	CAP, 33 μF, 20%, G CASE	1
J1, J2	CONN, SMA, PANEL MOUNT JACK, FLANGE	2
	PCB, RT5880, 0.020" THK, CGHV1F006S	1
	BASEPLATE, AL, 2.60 X 1.70 X 2.50	1
J3	HEADER RT>PLZ .1CEN LK 5POS	1
	2-56 SOC HD SCREW 1/4 SS	4
	#2 SPLIT LOCKWASHER SS	4
Q1	QFN TRANSISTOR CGHV1F006S	1

CGHV1F006S-AMP2 Application Circuit

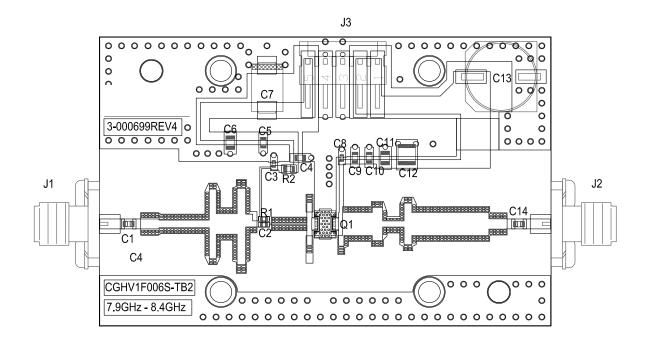




CGHV1F006S-AMP2 Application Circuit Schematic, SATCOM



CGHV1F006S-AMP2 Application Circuit Outline, SATCOM





Electrical Characteristics When Tested in CGHV1F006S-AMP3 at X-Band, RADAR

Characteristics	Symbol	Min.	Тур.	Max.	Units	Conditions	
RF Characteristics 1 ($T_c = 25$ °C, $F_0 = 8.5 - 9.6$ GHz unless otherwise noted)							
Gain	G	-	14.5	-	dB	$V_{DD} = 40 \text{ V}, I_{DQ} = 60 \text{ mA}, P_{IN} = 0 \text{ dBm}$	
Output Power ²	Роит	-	38.5	-	dBm		
Drain Efficiency ²	η	-	52	-	%	$V_{DD} = 40 \text{ V}, I_{DQ} = 60 \text{ mA}, P_{IN} = 28 \text{ dBm}$	
Output Mismatch Stress ²	VSWR	_	10:1	-	Ψ		

Notes:

Typical Performance in Application Circuit CGHV1F006S-AMP3 at X-Band, RADAR

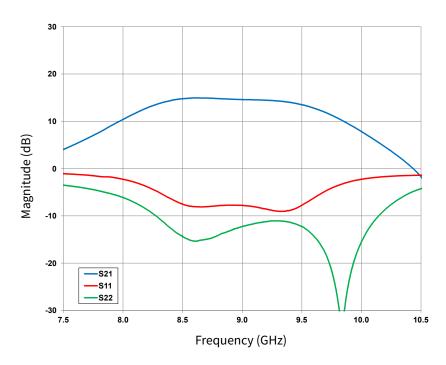


Figure 9. Typical Small Signal Response $V_{DD} = 40 \text{ V}, I_{DQ} = 60 \text{ mA}$

¹Measured in CGHV1F006S-AMP3 Application Circuit

 $^{^2}$ Pulsed 100 μ s, 10% duty cycle



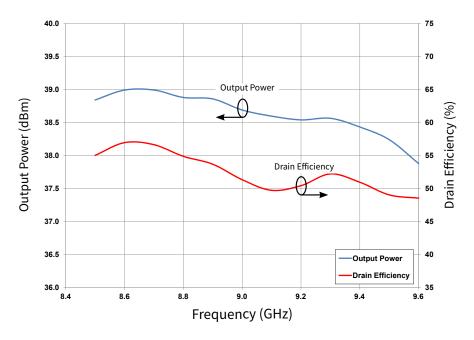
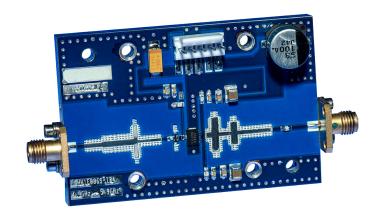


Figure 10. Typical Pulsed Power Response $V_{DD} = 40 \text{ V}, I_{DO} = 60 \text{ mA}, 100 \text{ } \mu\text{s}, 10\% \text{ Duty}, P_{IN} = 28 \text{ dBm}$

CGHV1F006S-AMP3 Application Circuit Bill of Materials, RADAR

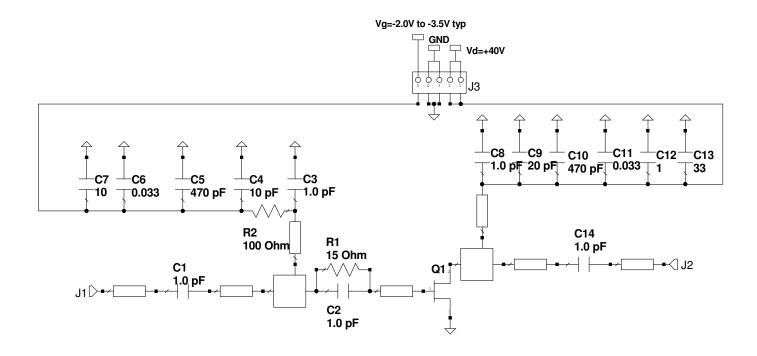
Designator	Description	Qty
R1	RES, 15 ohm, +1/-1%, 1/16 W, 0402	1
R2	RES, 100 ohm, +1/-1%, 1/16 W, 0603	1
C1, C14	CAP, 1.0 pF, ±0.05 pF, 0603, ATC	2
C2	CAP, 1.0 pF, ±0.05 pF, 0402, ATC	1
C3, C8	CAP, 0.8 pF, ±0.05 pF, 0402, ATC	2
C4	CAP, 10 pF, ±5%, 0603, ATC	1
C5, C10	CAP, 470 pF, 5%, 100 V, 0603, X	2
C6, C11	CAP, 33000 pF, 0805, 100V, X7R	2
C7	CAP, 10 μF, 16 V, TANTALUM	1
C9	CAP, 20 pF, ±5%, 0603, ATC	1
C12	CAP, 1.0 μF, 100V, 10% X7R, 1210	1
C13	CAP, 33 μF, 20%, G CASE	1
J1, J2	CONN, SMA, PANEL MOUNT JACK, FLANGE	2
J3	HEADER RT>PLZ .1CEN LK 5POS	1
Q1	QFN TRANSISTOR CGHV1F006S	1

CGHV1F006S-AMP3 Application Circuit

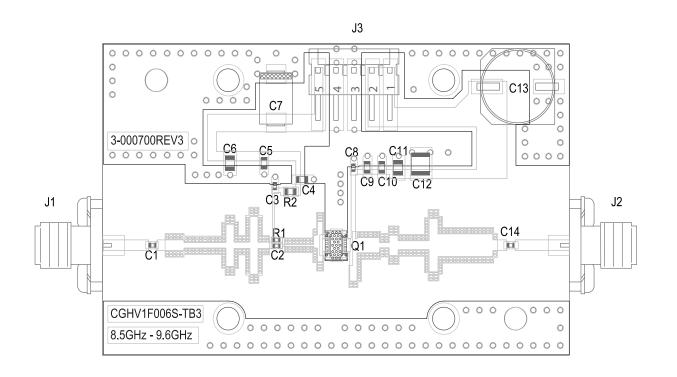




CGHV1F006S-AMP3 Application Circuit Schematic, RADAR



CGHV1F006S-AMP3 Application Circuit Outline, RADAR





Electrical Characteristics When Tested in CGHV1F006S-AMP4 at 802.11

Characteristics	Symbol	Min.	Тур.	Max.	Units	Conditions	
RF Characteristics ¹ (T _c = 25°C, F ₀ = 4.9 - 5.9 GHz unless otherwise noted)							
Gain	G	-	13	-	dB	V = 20 V L = 20 mA D = 27 dDm	
Drain Efficiency ²	η	-	27	-	%	$V_{DD} = 20 \text{ V, I}_{DQ} = 30 \text{ mA, P}_{IN} = 27 \text{ dBm}$	
OQPSK ³	ACLR	-	-43	-	dBc	V _{DD} = 20 V, I _{DQ} = 30 mA, P _{OUT} = 27 dBm	
Output Mismatch Stress ²	VSWR	-	10:1	-	Ψ	No damage at all phase angles, $V_{DD} = 20 \text{ V}, I_{DQ} = 30 \text{ mA}, P_{IN} = 27 \text{ dBm}$	

Notes:

Typical Performance - CGHV1F006S-AMP4 at 802.11

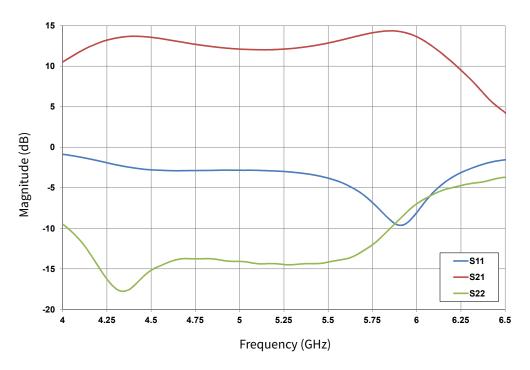


Figure 11. Typical Small Signal Response $V_{DD} = 20 \text{ V}, I_{DQ} = 30 \text{ mA}$

¹Measured in CGHV1F006S-AMP4 Application Circuit

² Single carrier WCDMA, 3GPP Test Model 1, G4 DPCH, 45% clipping, PAR = 7.5 dB @ 0.01% probability on CCDF



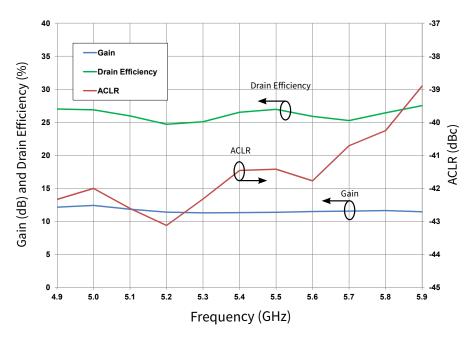
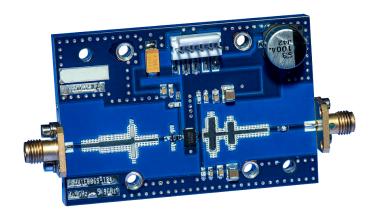


Figure 12. Typical Gain, Efficiency and WCDMA Performance vs Frequency $V_{DD} = 20 \text{ V}, I_{DO} = 30 \text{ mA}, P_{OUT} = 27 \text{ dBm}$

CGHV1F006S-AMP4 Application Circuit Bill of Materials at 802.11

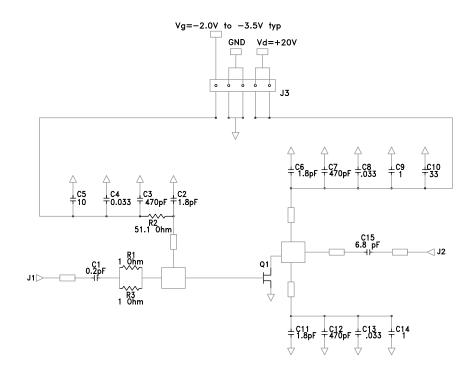
Designator	Description	Qty
R1, R3	RES, 1 ohm, +/-1%, 1/16 W, 0402	2
R2	RES, 51.1, ohm, +/-1%, 1/16W, 0603	1
C2, C6, C11	CAP, 1.8 pF, +/-0.1 pF, 0603, ATC	3
C1	CAP, 0.2 pF, +/-0.05 pF, 0402, ATC	1
C3, C7, C12	CAP, 470 pF, 5%, 100 V, 0603, X	3
C4, C8, C13	CAP, 33000 pF, 0805, 100 V, X7R	3
C5	CAP, 10 μF, 16 V, TANTALUM	1
C15	CAP, 6.8 pF, ±0.25 pF, 100 V, 0603	1
C9, C14	CAP, 1.0 μF, 100V, 10% X7R, 1210	2
C10	CAP, 33 μF, 20%, G CASE	1
J1, J2	CONN, SMA, PANEL MOUNT JACK, FLANGE	2
	PCB, RO4350B, 0.020" THK, CGHV1F006S	1
	BASEPLATE, CGH35015, 2.60 X 1.7	1
J3	HEADER RT>PLZ .1CEN LK 5POS	1
	2-56 SOC HD SCREW 1/4 SS	4
	#2 SPLIT LOCKWASHER SS	4
Q1	QFN TRANSISTOR CGHV1F006S	1

CGHV1F006S-AMP4 Application Circuit

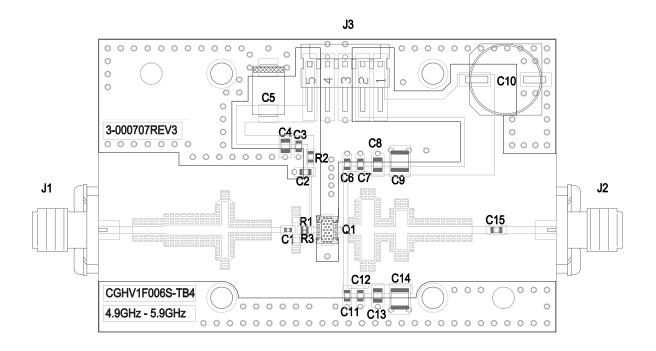




CGHV1F006S-AMP4 Application Circuit Schematic, SATCOM



CGHV1F006S-AMP4 Application Circuit Outline, SATCOM





CGHV1F006S Power Dissipation De-rating Curve

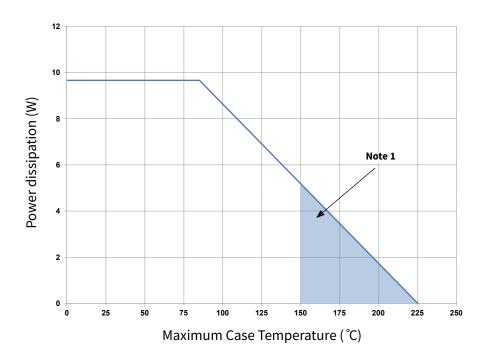


Figure 13. CGHV1F006S Transient Power Dissipation De-Rating Curve

Note:

Electrostatic Discharge (ESD) Classifications

Parameter	Symbol	Class	Classification Level	Test Methodology
Human Body Model	НВМ	1B	ANSI/ESDA/JEDEC JS-001 Table 3	JEDEC JESD22 A114-D
Charge Device Model	CDM	0CB	ANSI/ESDA/JEDEC JS-002 Table 3	JEDEC JESD22 C101-C

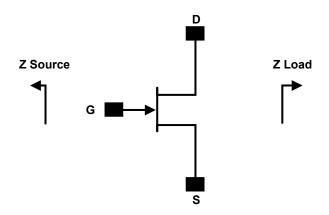
Moisture Sensitivity Level (MSL) Classification

Parameter	Symbol	Level	Test Methodology
Moisture Sensitivity Level	MSL	3 (168 hours)	IPC/JEDEC J-STD-20

¹ Area exceeds Maximum Case Temperature (See Page 2)



Source and Load Impedances



Frequency (GHz)	Z Source	Z Load
1	49.67 + j32.81	184.11 + j6.66
3	11.54 + j3.96	38.83 + j56.37
6	5.94 - j17.97	13.03 + j16.16
10	11.87 - j77.62	11.79 - j17.43
12	47.42 - j205.35	16.39 - j46.22
15	33.78 + j251.03	163.61 - j268.44

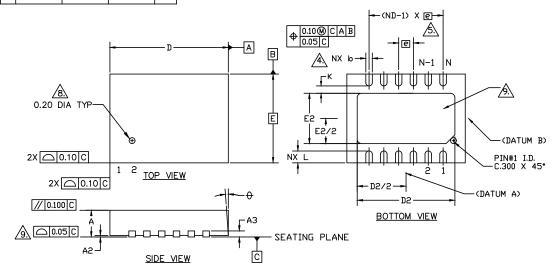
Notes:

 $^{^1}$ V $_{DD}$ = 40 V, I $_{DQ}$ = 60 mA 2 Impedances are extracted from source and load pull data derived from the transistor

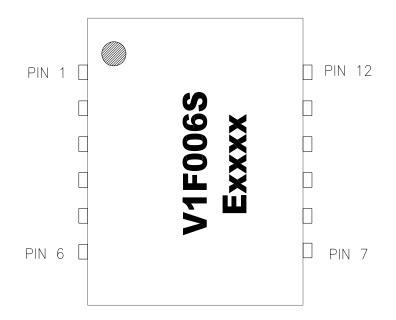


Product Dimensions CGHV1F006S (Package 3 x 4 DFN)

_				
SYMBO.	COMMON DIMENSIONS			N _O
٥	MIN.	NOM.	MAX.	NOTE
Α	0.80	0.90	1.0	
Α1	0.00	0.02	0.05	
Α3	(0.203 REF.		
θ	0		12	2
D	4.00 BSC			
Ε	3.00 BSC			
е	0.50 BSC			
N		12		
ND	6			Æ
L	0.35	0.40	0.45	
b	0.18	0.25	0.30	<u>A</u>
D2	3.20	3.30	3.40	
E2	1.60	1.7	1.80	
K	0.20			



Input/Output	
GND	
NC	
RF IN	
RF IN	
NC	
GND	
GND	
NC	
RF OUT	
RF OUT	
NC	
GND	





Part Number System

CGHV1F006S



Table 1.

Parameter	Value	Units
Upper Frequency ¹	15.0	GHz
Power Output	6	W
Package	Surface Mount	-

Note:

Table 2.

Character Code	Code Value
А	0
В	1
С	2
D	3
E	4
F	5
G	6
Н	7
J	8
К	9
Examples:	1A = 10.0 GHz 2H = 27.0 GHz

¹ Alpha characters used in frequency code indicate a value greater than 9.9 GHz. See Table 2 for value.



Product Ordering Information

Order Number	Description	Unit of Measure	Image
CGHV1F006S	GaN HEMT	Each	1 1 5 6 6 6 5 5 5 5 5 5 5 5 5 5 5 5 5 5
CGHV1F006S-AMP1	Test board with GaN HEMT installed, 5.85 - 7.2 GHz, 50 V C-Band under OQPSK	Each	
CGHV1F006S-AMP2	Test board with GaN HEMT installed, 7.9 - 8.4 GHz, 28 V X-Band SATCOM	Each	ENGLISHED OF THE PARTY OF THE P
CGHV1F006S-AMP3	Test board with GaN HEMT installed, 8.5 - 9.6 GHz, 28 V X-Band RADAR	Each	
CGHV1F006S-AMP4	Test board with GaN HEMT installed, 4.9 - 5.9 GHz, 50 V 802.11	Each	TOTAL STATE OF THE PARTY OF THE



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